

K1160AA™ **Dual Output**

Crystal Clock

Oscillators

2.4576 MHz to 10.0000 MHz (MOS) TTL output at twice MOS frequency

.820" x .520" AREA

ALL-METAL WELDED PACKAGE

INSULATED STANDOFFS

DUAL IN-LINE SPACING

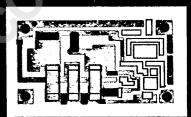
+5V dc INPUT

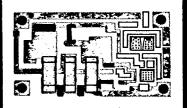
+0%, -0.02% STABILITY

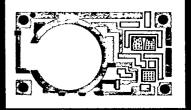
DESIGNED TO DRIVE

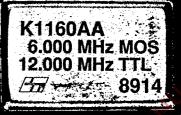
ZILOG Z8000 AND Z80A, Z8000A AND Z80B

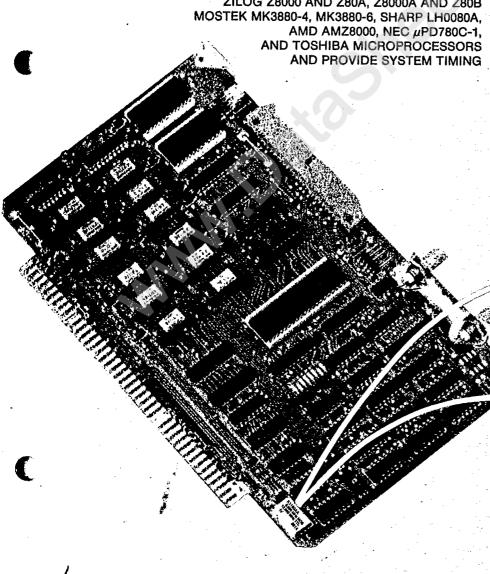












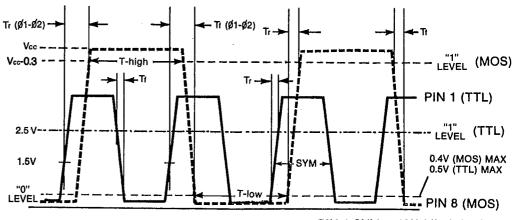
features

- MOS AND TTL OUTPUTS—The K1160AA, designed to drive Zilog Z80A, Z80B, Z8000-type or equivalent 8- and 16-bit microprocessors, is available with NMOS outputs covering a range of 2.4576 to 10 MHz. The oscillator also provides a TTL-compatible output at twice the processor frequency to satisfy system timing requirements.
- REDUCES COMPONENT COUNT
 —Single thick film hybrid clock with
 active pull-up on the output replaces
 approximately 17 discrete components
 required by conventional techniques.
 Reduced component count not only reduces required board space but also
 improves reliability.
- HIGH DENSITY PACKAGING—takes up only .820" x .520" on a circuit board, and its seated height of .270" lets you use standard logic boards with no loss of spacing. Can be soldered directly to the PCB or mounted in a DIP socket, according to your production needs.

The Parties

- +0%, -0.02% STABILITY—over the range of 0°C to 70°C, suitable for most applications in data communication logic timing. This specification is inclusive of calibration tolerance, stability vs. input voltage change, aging, and stability vs. shock and vibration.
- RUGGED, RELIABLE—maximum reliability at minimum cost is the result of combining two fields of experience; quartz crystal technology and thick film hybrid integrated circuit processing. Mass automated production technology

- niques assure volume production. High precision crystals and clean room processing testify that no shortcuts are taken that might diminish reliability. Environmental testing proves the effectiveness of the rugged design for those applications in which shock and vibration are common hazards.
- YOUR TIMING NEEDS IN ONE PACK-AGE—The K1160AA oscillator is designed to provide system timing requirements as well as to drive the microprocessor. The manufacturing savings inherent in this design are passed on to you, simplifying your make vs. buy decision. The K1160AA saves you the board space required by discrete components, and eliminates production man-hours wasted analyzing oscillator circuits and matching crystal parameters to circuit components. And with a packaged oscillator, you eliminate sourcehunting and source-qualifying for its components, cut down on direct labor for parts insertion, cut down on overhead costs for Receiving, Incoming Inspection, Purchasing, and Accounts Payable.
- COMPLETE PROCESS CONTROL
 —Uniform high quality in high volume production is made possible only by complete control of the manufacturing process, from finishing the quartz through hybrid thick film circuit processing and clean room assembly, with stringent quality control measures enforced.
- VOLUME PRODUCTION—Modern automated production techniques are used to provide high volume, high quality crystal clock oscillators.



PIN 1 SYM = 40% Min/60% Max Tr $(0_1 - 0_2)$ = 25 ns Max

Tr $(\emptyset_1 - \emptyset_2) = 25 \text{ ns Max}$

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CHAMPION TECHNOLOGIES INC 57E D pecifications

■ FREQUENCY:

Pin 8 (MOS): 2.4576 to 10.0000 MHz Pin 1 (TTL): twice the pin 8 frequency

FREQUENCY STABILITY: +0%, --.020% (Inclusive of calibration tolerance at 25°C operating temperature range, input voltage change, load change, aging, shock, and vibration.)

TEMPERATURE RANGE:

OPERATING: STORAGE:

0°C to 70°C -55°C to +125°C

■ INPUT VOLTAGE:

+5V dc ±10%

INPUT POWER: 357 mW maximum

INPUT CURRENT:

65 mA max @ 2.4576 to 4.999 MHz Pin 8 80 mA max @ 5.000 to 6.000 MHz Pin 8 90 mA max @ 6.001 to 10.000 MHz Pin 8

STEADY-STATE LIFE:

MIL-STD-883B, Method 1005 1000 hrs @ 125°C, disregarding

Leak test in de-ionized H2O.

Mass spectrometer leak rate less than 2×10^{-8} atmos. cc/sec. of

20 lbs. max. force perpendicular

frequency shift.

MIL-STD-883B, Method 3015 Class B; >2 KV

-50*-*2:

SENSITIVITY: **MECHANICAL: GROSS LEAK**

ELECTROSTATIC DISCHARGE

TEST: HERMETICALLY SEALED PACKAGE:

STRENGTH:

MARKING INK:

RESISTANCE:

SOLVENT

BEND TEST:

to top and bottom Pins will withstand maximum bend of 90° reference to base for 2 bends.

Epoxy, heat cured

Isopropyl alcohol, Tricholoroethane Freon TMC

helium

No marking or seal destruction

Dipped 1 minute @ +25° C ±5° C in solvent Note: (1) Unit can be cleaned by only one type solvent listed.

Note: (2) Ultrasonic degreaser not to be used.

		2.4576-4.000 MHz MOS				4.001-6.000 MHz MOS				6.001-10.000 MHz MOS			
SYMBOL	DESCRIPTION	PIN 1		PIN 8		PIN 1		PIN 8		PIN 1		PIN 8	
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX
Fo	Output Frequency	2 x Fo Pin 8		2.5 MHz	4 MHz	2 x Fo Pin 8		4.001 MHz	6 MHz	2 x Fo Pin 8		6.001 MHz	10 MHz
	Load		10 TTL		150 pf		10 TTL		150 pf	_	10 TTL		100 pt
t (ØH)	Pulse Width Clock High (sec)	_	_	(.5/F _o) -15 ns	·	-		.42/Fo	,	-	-	.5/F₀ −10 ns	
t (ØL)	Pulse Width Clock Low (sec)	-	-	(.5/F ₀) -15 ns		_	-	.42/Fo		-	_	.5/F₀ −10 ns	
Ta	Clock Rise Time	_	10 ns		15 ns	_	10 ns	_	10 ns	_	10 ns	. —	10 ns
TF	Clock Fall Time	-	10 ns	_	15 ns	_	10 ns	-	10 ns	_	10 ns		10 ns
VIL VIH	Low Level High Level	-0.3V 2.5V	0.5V 	 Vcc3V	0.4V Vcc	-0.3V 2.5V	0.5V 	Vcc3V	0.4V Vcc	-0.3V 2.5V	0.5V	 Vcc3V	0.4V Vcc

(Symmetry and phase relationship expressed on front page wave form.)

ENVIRONMENTAL:

TEMPERATURE CYCLE:

MIL-STD-883B Method 1010.2

1000 G's 0.35 millisec, 1/2 sine wave;

VIBRATION:

SHOCK:

3 shocks each plane 10-55 Hz, .060" D.A., 55 Hz-2000 Hz

35 G's. Duration time-12 hours 85% Relative humidity, @ +85° C, 500 hrs.

HUMIDITY:

rolderability rpecifications

MATERIALS:

SOLDER:

60% tin and 40% lead

FLUX:

Mildly activated rosin base type such as Alpha 611.

FROCEDURE:

PREPARATION:

No wiping, cleaning, scraping, or abrading shall be performed on the leads. The solder bath shall be maintained at

SOLDER BATH:

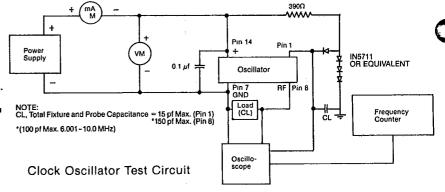
265 ±5°C.

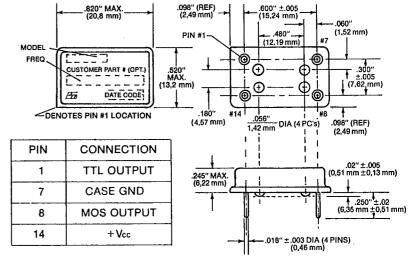
SOLDERABILITY: Dip the terminals into room temperature flux, to a maximum of .020" from the unit base, for 5 to 10 seconds. Withdraw from the flux and dip the terminals to the same depth in the molten solder from 5 to 7 seconds. Flux residue may be removed with Freon rinse, or with soft swab moistened with isopropyl alcohol or Freon.

REQUIREMENTS: EVALUATION:

All leads must exhibit a minimum of 90% continuous solder coating over their entire length beyond .020° from the unit base. Pinholes or voids may not be concentrated in any one area and are not to exceed 10% of the total area under examination.

Zilog, Z8000, Z80A, Z8000A, Z80B, Mostek, MK3880-4, MK3880-6, Sharp, LH0080A, AMD, AMZ8000, NEC μPD780C₅1, and Toshiba are trademarks of their respective companies.





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